



### SNC50HXP

A lower deflection force, nickel/graphite filled heat curable silicone Form-In-Place grade. Thanks to its unique filler technology, SNC50 HXP shows the lowest shore hardness in Laird's cure FIP resulting in minimum required compression force when mounting assemblies. It shows very good shielding performance along with good compression set ending in overall long-term reliability.

Laird's Form-In-Place is an automated system for dispensing conductive elastomer EMI shielding and grounding gaskets onto metal or plastic substrates. All Laird Paste can be dispensed to triangular profile directly.

### TYPICAL VALUES

	TEST METHOD	UNITS	SNC50 HXP
<b>Elastomer</b>			Silicone
<b>Filler Type</b>			Nickel/Graphite
<b>ELECTRICAL PROPERTIES</b>			
<b>Volume Resistivity</b>	WI-QA-4153	ohm-cm	< 0.025
<b>Shielding Effectiveness, 200 MHz to 10 GHz</b>	MIL-DTL-83528C, Para. 4.5.12	dB	120 (Avg.)
<b>PHYSICAL PROPERTIES</b>			
<b>Hardness</b>	ASTM D2240	Shore A	50
<b>Density (uncured)</b>	ASTM D792	g/cm <sup>3</sup>	1.80
<b>(cured)</b>		g/cm <sup>3</sup>	2.10
<b>Compression Set</b>	ASTM D395	%	20
	125°C, 22hrs		
<b>Adhesion Strength</b>	to Aluminum surface	N/cm <sup>2</sup>	>100
<b>Compression-Deflection <sup>(a)</sup></b>	LT-FIP-CLE-07		
<b>at 20% compression</b>		lb/in	2.60
<b>at 40% compression</b>		lb/in	9.50
<b>Temperature Range</b>		°C	-55 to 125
<b>UL Flammability Rating</b>	UL94 (between AI)		V0

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## Form-In-Place

CURING REQUIREMENTS	
<b>Curing Conditions</b>	125°C Min.
<b>Full Cure<sup>(b)</sup></b>	1 hour

(a) Compression-deflection bead size 0.7mm (H) × 0.80mm (W)

(b) Time to effectively cure a bead will necessarily depend on individual conditions, including but not limited to bead size, shield size and weight, oven capacity, and oven ramp-rates.